PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

Assignment ID: PATI704852

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Roger D. Burdi	06/30/2004
Bruce L. Reniger	06/30/2004

RECEIVING PARTY DATA

Company Name:	Material Sciences Corporation
Street Address:	2200 East Pratt Boulevard
City:	Elk Grove Village
State/Country:	ILLINOIS
Postal Code:	60007

PROPERTY NUMBERS Total: 1

Property Type	Number
Patent Number:	8024967

CORRESPONDENCE DATA

Fax Number: 3124568435

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: (312)456-1009
Email: knisera@gtlaw.com
Correspondent Name: Jonathan Giroux
Address Line 1: 77 W. Wacker Drive
Address Line 2: Suite 3100
Address Line 4: Chicago, ILLINOIS 60601

ATTORNEY DOCKET NUMBER:	214453-010000
NAME OF SUBMITTER:	Amber Kniser
SIGNATURE:	Amber Kniser
DATE SIGNED:	12/18/2024

Total Attachments: 3
source=Assignment#page1.tiff
source=Assignment#page2.tiff
source=Assignment#page3.tiff

ASSIGNMENT

In consideration for One Dollar and other good and valuable consideration, receipt of which is hereby acknowledged, We, Roger D. Burdi, of 5635 Ada Drive, SE, Grand Rapids, Michigan 49546 and Bruce L. Reniger, of 11693 84th St., Alto, Michigan 49302, hereby sell, assign, transfer and set over to Material Sciences Corporation, Electronic Materials and Devices Group, Inc. having its principal place of business at 2200 East Pratt Boulevard, Elk Grove Village, IL, 60007-5995, its successors, assigns, nominees, or other legal representatives, the entire right, title and interest in all countries including the priority rights derived from the hereinafter designated application for Letters Patent by virtue of the International Convention for the Protection of Industrial Property for any and all member countries of the aforesaid International Convention, in and to the invention or inventions made by us for SOLID STATE FLUID LEVEL SENSOR and the application for Letters Patent of the United States therefor, executed by us on or about June 30 _________, 2004, and bearing a filing date of ____________________, and a Serial No. __________________ together with all rights, including the sole rights under the aforesaid International Convention to apply for and obtain Letters Patent for said invention or inventions in the United States and in all other countries of the world, including original, divisional, continuation, continuation-in-part, reissue, utility and design patents, patents of addition, confirmation patents, registration patents, petty patents, utility models, etc., and all other types of patents and the like, and all renewals and extensions of any of them, and the entire right, title and interest in and to all such Letters Patent, the applications therefor and the subject matter of all claims obtained in said Letters Patent, and authorize and request the Commissioner of Patents and Trademarks of the United States, and any official of any country or countries foreign to the United States whose duty it is to issue Letters Patent on applications as aforesaid to issue the said Letters Patent to the Material Sciences Corporation, its successors, assigns, nominees or other legal representatives, as assignee of the entire interest, and covenant that we convey the entire interest herein assigned and that we have not executed and will not execute any agreement in conflict herewith.

Wefurther covenant and agree that whenever requested by said Material Sciences Corporation, its successors, assigns, nominees or legal representatives, we will execute and deliver or cause to be executed and delivered such further patent applications, assignments, oaths, disclaimers and other documents, give or cause to be given such evidence and furnish or cause to be furnished such information within my knowledge or control, and do or cause to be done such other acts and furnish or cause to be furnished such other assistance, as it or any of them may deem necessary or desirable in connection with obtaining and/or maintaining any Letters Patent as aforesaid for said invention or inventions, or in connection with any suit or controversy, including interference proceedings, relating to any of such Letters Patent or to any applications therefor or in order to vest or perfect in it or in any of them or to protect or enforce the right, title and interest herein assigned, or otherwise effectuate the premises, all without further consideration but at the expense of said Material Sciences Corporation, its successors, assigns, nominees or other legal representatives.

We hereby grant to Joseph W. Berenato, [redacted] of Liniak, Berenato & White, LLC, full power to insert herein the execution and filing dates and serial number of the application for Letters Patent of the United States first above mentioned.

Date: 6/30/04

Richard D. Burdi

Date: 6/30/04

Bruce L. Reniger